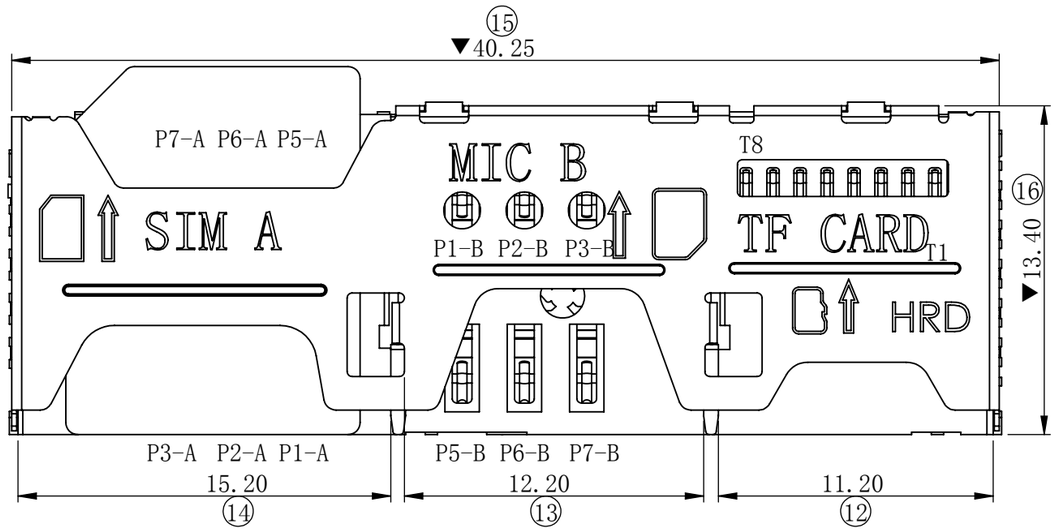
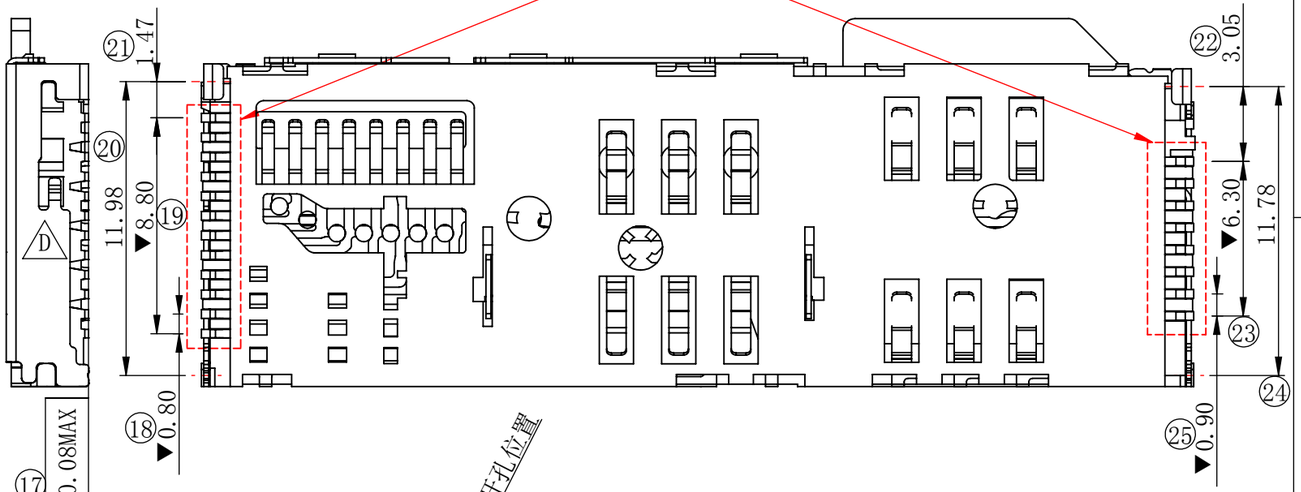
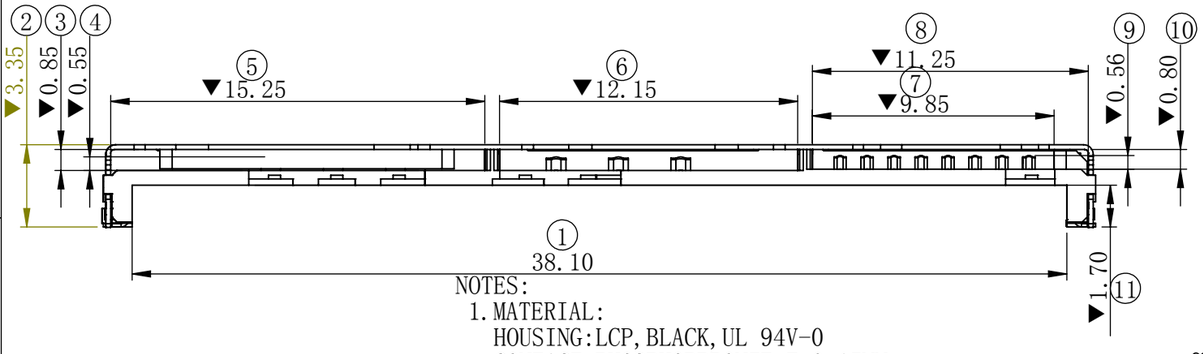
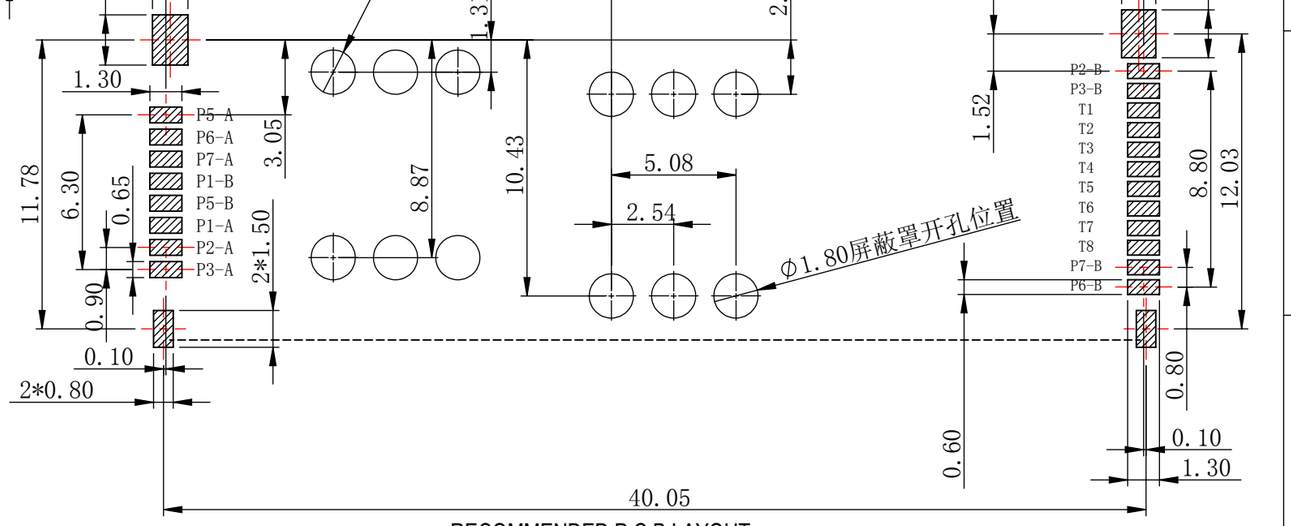






NOTES:
1. MATERIAL:
   HOUSING:LCP,BLACK,UL 94V-0
   CONTACT:PHOSPHORBRONZE,T=0.15MM
   SHELL:STAINLESS STEEL T=0.20MM
2. FININSH
   CONTACT: 50U'' MIN PLATING OVER ALL
   GOLD FLASH ON THE CONTACT AREA AND SOLDER AREA
   SHELL:SELECTIVE GOLD FLASH IN SOLDER TAIL AREA
   50U'' NI MIN. PLATING OVER ALL
3. ALL DIMENSIONS MARKED ▼ MUST BE CONTROLLED BY QC
4. GP PASSED ACCORD WITH HRD-RoHS-219 STANDARD.
5. ALL DIMENSIONS MARKER (XX) MUST BE MEASURE BY FAI.
6. RATED PARAMETERS OF CONNECTOR
   4-1. Operating temperature: -40℃ to 70℃
   4-2. Rated Current: 0.5A
   4-3. Rated Voltage: 30V DC Per Contact
7. ELECTRICAL MECHANICAL ENVIRONMENTAL
   5-1. Dielectric withstanding Voltage : 500V AC 1min.
   5-2. Insulation Resistance: 1000 MΩMin.
   5-3. Normal Force: 100g Min. Per Pin
   5-4. Durability: 3000 cycles
   5-5. Heat Resistance: 20mΩ MAX.

T-CARD PIN NO.	PIN NO.
T1	DAT2
T2	CD/DAT3
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DATO
T8	DAT1
SIM CARD PIN NO.	PIN NO.
P1-A/B	VCC
P2-A/B	RST
P3-A/B	CLK
P5-A/B	GND
P6-A/B	VPP
P7-A/B	I/O



RECOMMENDED P.C.B LAYOUT
TOLERANCE:±0.05MM

REV.	ECN NO.	DESCRIPTION	DATE
E	E1912709A	锡脚加胶	12/09/2019
D	E1610460A	铁壳变更	10/27/2016
C	E1608312A	修改图面与实物一致	08/04/2016
B	E1503125A	结构变更	03/11/2015

UNITS: mm
DATE: 08/14/2014
SCALE: 4 : 1
SHEET: 1 / 1
REV. A

GENERAL TOLERANCE

X.	±0.25	X°	±5.00°
.X	±0.20	.X°	±3.00°
.XX	±0.10	.XX°	±1.00°
.XXX	±0.05		

MATERIAL:
FINISH: SEE NOTE

DRAW:
CHECKED:
APPROVE:

PART NO: S39-1B20F33A
TITLE: SIM CARD&SMALL CARD&TF CARD 3.35H
DRAWING NO:

昆山捷皇电子精密科技有限公司
HONGRIDA ELECTRONIC TECHNOLOGY CO,LTD.